

3-wire Serial EEPROM 16K (2,048 x 8 or 1,024 x 16)

DATASHEET

Features

- Low-voltage Operation
 - V_{CC} = 1.8V to 5.5V
 - V_{CC} = 2.7V to 5.5V
- User-selectable Internal Organization
 - 16K: 2,048 x 8 or 1,024 x 16
- 3-wire Serial Interface
- Sequential Read Operation
- Schmitt Trigger, Filtered Inputs for Noise Suppression
- 2MHz Clock Rate (5V)
- Self-timed Write Cycle (10ms Max)
- High Reliability
 - Endurance: 1,000,000 Write Cycles
 - Data Retention: 100 Years
- 8-lead JEDEC SOIC, 8-lead TSSOP, 8-pad UDFN, and 8-lead PDIP Packages

Description

The Atmel® AT93C86A provides 16,384 bits of Serial Electrically Erasable Programmable Read-Only Memory (EEPROM) organized as 1,024 words of 16 bits each (when the ORG pin is connected to $V_{\rm CC}$) and 2,048 words of 8 bits each (when the ORG pin is tied to ground). The device is optimized for use in many industrial and commercial applications where low-power and low-voltage operations are essential. The AT93C86A is available in space-saving 8-lead JEDEC SOIC, 8-lead TSSOP, 8-pad UDFN, and 8-lead PDIP packages.

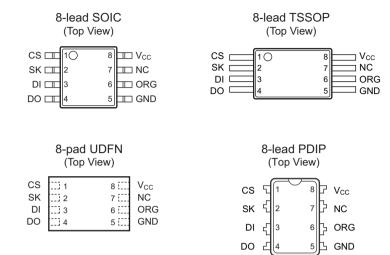
The AT93C86A is enabled through the Chip Select pin (CS) and accessed via a 3-wire serial interface consisting of Data Input (DI), Data Output (DO), and Shift Clock (SK). Upon receiving a Read instruction at DI, the address is decoded, and the data is clocked out serially on the DO pin. The write cycle is completely self-timed, and no separate erase cycle is required before Write. The write cycle is only enabled when the part is in the Erase/Write Enable state. When CS is brought high following the initiation of a write cycle, the DO pin outputs the Ready/Busy status of the part.

The AT93C86A operates from 1.8V to 5.5V or from 2.7V to 5.5V.

1. Pin Configurations and Pinouts

Table 1-1. Pin Configurations

Pin Name	Function
CS	Chip Select
SK	Serial Data Clock
DI	Serial Data Input
DO	Serial Data Output
GND	Ground
V _{CC}	Power Supply
ORG	Internal Organization
NC	No Connect



Note: Drawings are not to scale.

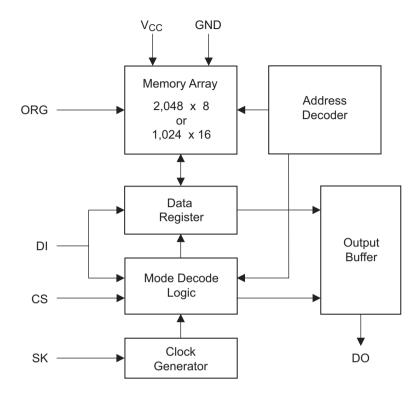
2. Absolute Maximum Ratings*

Operating Temperature55°C to +125°C
Storage Temperature65°C to +150°C
Voltage on any pin with respect to ground1.00V to +7.00V
Maximum Operating Voltage 6.25V
DC Output Current

*Notice: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

3. Block Diagram

Figure 3-1. Block Diagram



Note: When the ORG pin is connected to V_{CC} , the x16 organization is selected. When it is connected to ground, the x8 organization is selected. If the ORG pin is left unconnected, and the application does not load the input beyond the capability of the internal $1M\Omega$ pull-up resistor, then the x16 organization is selected.



4. Memory Organization

4.1 Pin Capacitance

Table 4-1. Pin Capacitance⁽¹⁾

Applicable over recommended operating range from $T_A = 25^{\circ}C$, f = 1.0MHz, $V_{CC} = 5.0V$ (unless otherwise noted).

Symbol	Test Conditions	Max	Units	Conditions
C _{OUT}	Output Capacitance (DO)	5	pF	V _{OUT} = 0V
C _{IN}	Input Capacitance (CS, SK, DI)	5	pF	V _{IN} = 0V

Note: 1. This parameter is characterized, and is not 100% tested.

4.2 DC Characteristics

Table 4-2. DC Characteristics

Applicable over recommended operating range from T_{AI} = -40°C to +85°C, V_{CC} = 1.8V to 5.5V (unless otherwise noted).

Symbol	Parameter	Test Condition	Min	Тур	Max	Unit	
V _{CC1}	Supply Voltage		1.8		5.5	V	
V _{CC2}	Supply Voltage			2.7		5.5	V
V _{CC3}	Supply Voltage			4.5		5.5	V
1	Supply Current	V _{CC} = 5.0V	Read at 1.0MHz		0.5	2.0	mA
I _{CC}	Supply Current	V _{CC} = 3.0V	Write at 1.0MHz		0.5	2.0	mA
I _{SB1}	Standby Current	V _{CC} = 1.8V	CS = 0V		0.4	1.0	μA
I _{SB2}	Standby Current	V _{CC} = 2.7V	CS = 0V		6.0	10.0	μA
I _{SB3}	Standby Current	V _{CC} = 5.0V		10.0	15.0	μA	
I _{IL}	Input Leakage	V _{IN} = 0V to V _{CC}			0.1	3.0	μA
I _{OL}	Output Leakage	V_{IN} = 0V to V_{CC}			0.1	3.0	μA
V _{IL1} ⁽¹⁾	Input Low Voltage	$2.7V \leq V_{CC} \leq 5.5V$		-0.6		0.8	V
V _{IH1} ⁽¹⁾	Input High Voltage	$2.7V \leq V_{CC} \leq 5.5V$		2.0		V _{CC} + 1	V
V _{IL2} ⁽¹⁾	Input Low Voltage	$1.8V \leq V_{CC} \leq 2.7V$		-0.6		V _{CC} x 0.3	V
V _{IH2} ⁽¹⁾	Input High Voltage	$1.8V \leq V_{CC} \leq 2.7V$	$1.8V \le V_{CC} \le 2.7V$			V _{CC} + 1	V
V _{OL1}	Output Low Voltage	$2.7V \le V_{CC} \le 5.5V$ $I_{OL} = 2.1mA$				0.4	V
V _{OH1}	Output High Voltage	$2.7V \le V_{CC} \le 5.5V$ $I_{OH} = -0.4mA$		2.4			V
V _{OL2}	Output Low Voltage	$1.8V \leq V_{CC} \leq 2.5V$	I _{OL} = 0.15mA			0.2	V
V _{OH2}	Output High Voltage	$1.8V \leq V_{CC} \leq 2.7V$	$I_{OH} = -100 \mu A$	V _{CC} - 0.2			V

Note: 1. V_{IL} min and V_{IH} max are reference only, and are not tested.



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4.3 AC Characteristics

Table 4-3. AC Characteristics

Applicable over recommended operating range from T_{AI} = -40°C to + 85°C, CL = 1 TTL gate and 100pF (unless otherwise noted).

Symbol	Parameter	Test Condition	Min	Тур	Max	Units	
		$4.5V \le V_{CC} \le 5.$	$4.5V \le V_{CC} \le 5.5V$			2	MHz
f _{SK}	SK Clock Frequency	$2.7V \le V_{CC} \le 5.$	$2.7V \leq V_{CC} \leq 5.5V$			1	MHz
		$1.8V \le V_{CC} \le 5.$	5V	0		250	kHz
4	SK High Time	$2.7V \le V_{CC} \le 5.$	5V	250			ns
t _{SKH}	SK High Time	$1.8V \le V_{CC} \le 5.$	5V	1000			ns
4	SK Low Time	$2.7V \le V_{CC} \le 5.$	5V	250			ns
t _{SKL}	SK LOW TIME	$1.8V \le V_{CC} \le 5.$	5V	1000			ns
4	Minimum CC Law Time	2.7V ≤ V _{CC} ≤ 5.	5V	250			ns
t _{CS}	Minimum CS Low Time	$1.8V \le V_{CC} \le 5.$	5V	1000			ns
4	CC Catus Time	Dolotivo to CV	$2.7V \le V_{CC} \le 5.5V$	50			ns
t _{CSS}	CS Setup Time	Relative to SK	$1.8V \le V_{CC} \le 5.5V$	200			ns
4	DI Cotus Timo	Relative to SK	$2.7V \leq V_{CC} \leq 5.5V$	100			ns
t _{DIS}	DI Setup Time		$1.8V \le V_{CC} \le 5.5V$	400			ns
t _{CSH}	CS Hold Time	Relative to SK		0			ns
4	DI Hold Time	Relative to SK	$2.7V \le V_{CC} \le 5.5V$	100			ns
t _{DIH}	DI Hold Time	Relative to SK	$1.8V \le V_{CC} \le 5.5V$	400			ns
4	Output Dolay to 1	AC Test	$2.7V \le V_{CC} \le 5.5V$			250	ns
t _{PD1}	Output Delay to 1	AC 1651	$1.8V \le V_{CC} \le 5.5V$			1000	ns
4	Output Dolov to 0	A.C. Toot	$2.7V \le V_{CC} \le 5.5V$			250	ns
t _{PD0}	Output Delay to 0	AC Test	$1.8V \le V_{CC} \le 5.5V$			1000	ns
4	CS to Status Valid	AC Test	$2.7V \le V_{CC} \le 5.5V$			250	ns
t _{SV}	CS to Status Valid	AC 1651	$1.8V \le V_{CC} \le 5.5V$			1000	ns
+	CS to DO in	AC Test	$2.7V \le V_{CC} \le 5.5V$			150	ns
t _{DF}	High-impedance	CS = V _{IL}	$1.8V \le V_{CC} \le 5.5V$			400	ns
t _{WP}	Write Cycle Time		0.1	3	10	ms	
Endurance ⁽¹⁾	5.0V, 25°C				1,000,000)	Write Cycles

Note: 1. This parameter is characterized, and is not 100% tested.



5. Functional Description

The AT93C86A is accessed via a simple and versatile 3-wire serial communication interface. Device operation is controlled by seven instructions issued by the Host processor. A valid instruction starts with a rising edge of CS and consists of a Start bit (Logic 1), followed by the appropriate opcode, and the desired memory address location.

Table 5-1. AT93C86A Instruction Set

			Addr	ess	Data		
Instruction	SB	Opcode	x8 ⁽¹⁾	x16 ⁽¹⁾	x8	x16	Comments
READ	1	10	$A_{10} - A_0$	$A_9 - A_0$			Reads data stored in memory at specified address.
EWEN	1	00	11XXXXXXX	11XXXXXX			Write Enable must precede all programming modes.
ERASE	1	11	$A_{10} - A_0$	$A_9 - A_0$			Erases memory location $A_N - A_0$.
WRITE	1	01	$A_{10} - A_0$	$A_9 - A_0$	D ₇ – D ₀	D ₁₅ - D ₀	Writes memory location $A_N - A_0$.
ERAL	1	00	10XXXXXXX	10XXXXXX			Erases all memory locations. Valid only at V_{CC} = 4.5V to 5.5V.
WRAL	1	00	01XXXXXXX	01XXXXXX	D ₇ – D ₀	D ₁₅ – D ₀	Writes all memory locations. Valid only at V_{CC} = 4.5V to 5.5V and Disable Register cleared.
EWDS	1	00	00XXXXXX	00XXXXXX			Disables all programming instructions.

Note: 1. The 'X' in the address field represent don't care values, and must be clocked.

READ: The READ instruction contains the address code for the memory location to be read. After the instruction and address are decoded, data from the selected memory location is available at the Serial Output pin, DO. Output data changes are synchronized with the rising edges of the Serial Clock pin, SK. It should be noted that a dummy bit (Logic 0) precedes the 8-bit or 16-bit data output string. The AT93C86A supports sequential Read operations. The device will automatically increment the internal address pointer and clock out the next memory location as long as Chip Select (CS) is held high. In this case, the dummy bit (Logic 0) will not be clocked out between memory locations, thus allowing for a continuous stream of data to be read.

Erase/Write Enable (EWEN): To ensure data integrity, the part automatically goes into the Erase/Write Disable (EWDS) state when power is first applied. An Erase/Write Enable (EWEN) instruction must be executed first before any programming instructions can be carried out.

Note: Once in the EWEN state, programming remains enabled until an EWDS instruction is executed, or V_{CC} power is removed from the part.

ERASE: The ERASE instruction programs all bits in the specified memory location to the Logic 1 state. The self-timed erase cycle starts once the ERASE instruction and address are decoded. The DO pin outputs the Ready/Busy status of the part if CS is brought high after being kept low for a minimum of t_{CS} . A Logic 1 at the DO pin indicates that the selected memory location has been erased, and the part is ready for another instruction.

WRITE: The WRITE instruction contains the 8-bits or 16-bits of data to be written into the specified memory location. The self-timed programming cycle, t_{WP} , starts after the last bit of data is received at Serial Data Input pin DI. The DO pin outputs the Ready/Busy status of the part if CS is brought high after being kept low for a minimum of t_{CS} . A Logic 0 at DO indicates that programming is still in progress. A Logic 1 indicates that the memory location at the specified address has been written with the data pattern contained in the instruction, and the part is ready for further instructions. A Ready/Busy status cannot be obtained if CS is brought high after the end of the self-timed programming cycle, t_{WP} .

Erase All (ERAL): The Erase All (ERAL) instruction programs every bit in the Memory Array to the Logic 1 state and is primarily used for testing purposes. The DO pin outputs the ready/busy status of the part if CS is brought high after being kept low for a minimum of t_{CS} . The ERAL instruction is valid only at V_{CC} = 5.0V ± 10%.

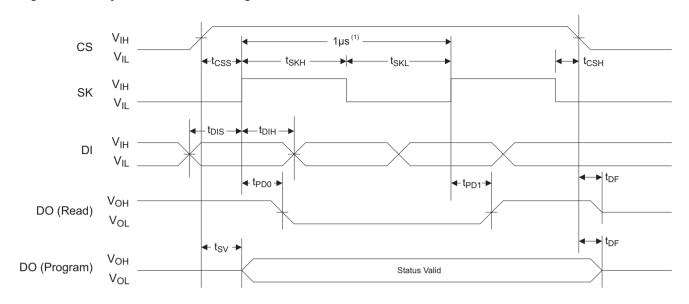
Write All (WRAL): The Write All (WRAL) instruction programs all memory locations with the data patterns specified in the instruction. The DO pin outputs the Ready/Busy status of the part if CS is brought high after being kept low for a minimum of t_{CS} . The WRAL instruction is valid only at V_{CC} = 5.0V ± 10%.

Erase/Write Disable (EWDS): To protect against accidental data disturbance, the Erase/Write Disable (EWDS) instruction disables all programming modes and should be executed after all programming operations. The operation of the Read instruction is independent of both the EWEN and EWDS instructions and can be executed at any time.



6. Timing Diagrams

Figure 6-1. Synchronous Data Timing

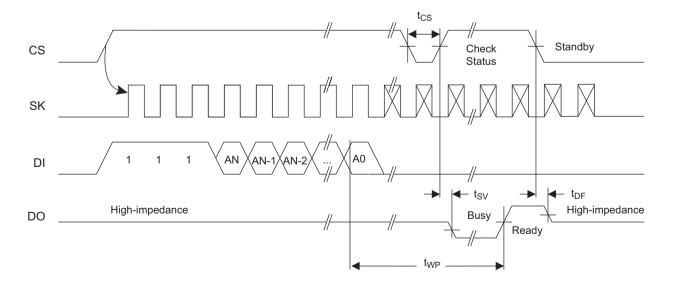


Note: 1. This is the minimum SK period.

Table 6-1. Organization Key for Timing Diagrams

	AT93C86A (16K)					
I/O	x8	x16				
A _N	A ₁₀	A ₉				
D _N	D ₇	D ₁₅				

Figure 6-2. ERASE Timing



8

Figure 6-3. READ Timing

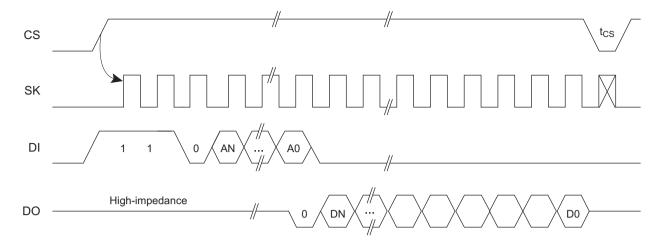


Figure 6-4. EWEN Timing

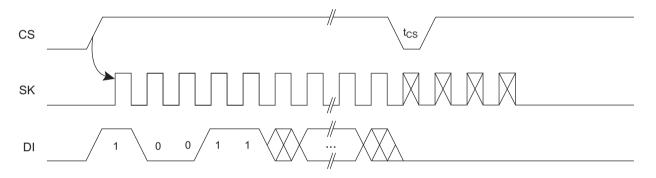


Figure 6-5. WRITE Timing

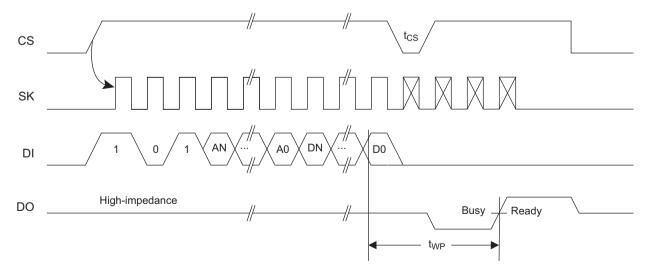
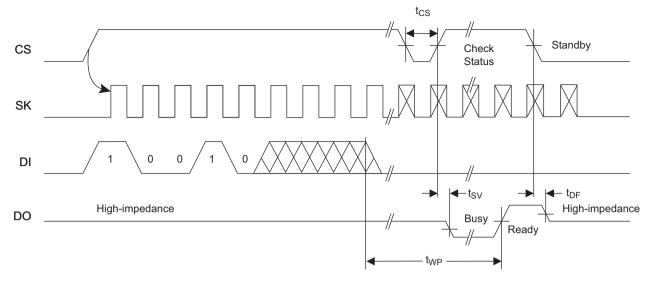


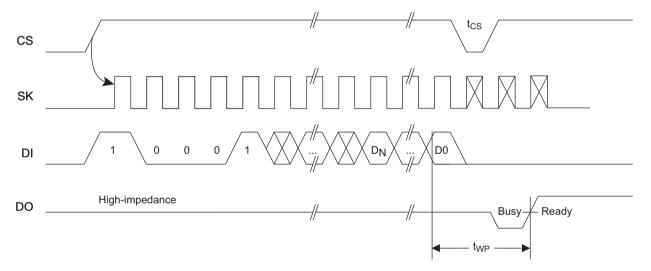


Figure 6-6. ERAL Timing⁽¹⁾



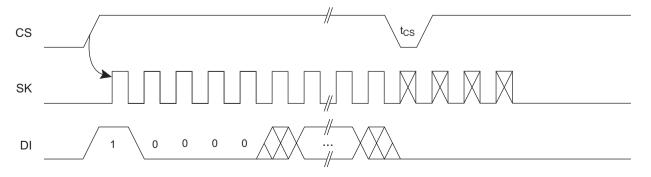
Note: 1. $V_{CC} = 4.5V$ to 5.5V.

Figure 6-7. WRAL Timing⁽¹⁾



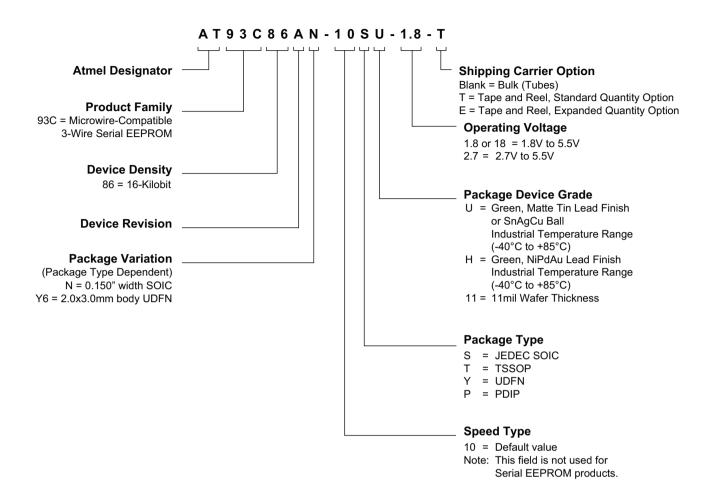
Note: 1. Valid only at V_{CC} = 4.5V to 5.5V.

Figure 6-8. EWDS Timing



10

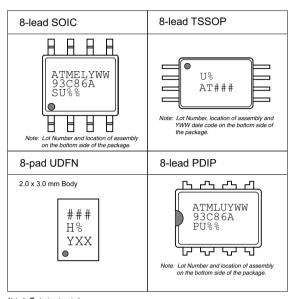
7. Ordering Code Detail





8. Part Markings

AT93C86A: Package Marking Information



Note 1: designates pin 1

Note 2: Package drawings are not to scale

Catalog Number Truncation								
AT93C86A Truncation Code ###: 86A								
Date Codes					Voltages			
Y = Year	0.0040	M = Month		WW = Work Week of Assembly	% = Minimum Voltage			
4: 2014 5: 2015 6: 2016 7: 2017	8: 2018 9: 2019 0: 2020 1: 2021	A: January B: Februar L: Decemb	y	02: Week 2 04: Week 4 52: Week 52	3 or 27: 2.7V min 1 or 18: 1.8V min			
Country of	Assembly	•	Lot Number		Grade/Lead Finish Material			
@ = Country of Assembly		AAAA = Atmel Wafer Lot Number		H: Industrial/NiPdAu U: Industrial/Matte Tin/SnAgCu				
Trace Code					Atmel Truncation			
XX = Trace Code (Atmel Lot Numbers Correspond to Code) Example: AA, AB YZ, ZZ				AT: Atmel ATM: Atmel ATML: Atmel				

6/11/14

Atmel	TITLE	DRAWING NO.	REV.
Package Mark Contact: DL-CSO-Assy_eng@atmel.com	93C86ASM, AT93C86A Package Marking Information	93C86ASM	А



9. Ordering Information

	Lead Delivery Information		Operation				
Atmel Ordering Code ⁽¹⁾	Finish	Package	Voltage	Form	Quantity	Range	
AT93C86A-10SU-1.8			1.8V to 5.5V	Bulk (Tubes)	100 per Tube	Industrial Temperature (-40°C to 85°C)	
AT93C86A-10SU-1.8-T		8S1	1.8V to 5.5V	Tape and Reel	4,000 per Reel		
AT93C86A-10SU-2.7			2.7V to 5.5V ⁽¹⁾	Bulk (Tubes)	100 per Tube		
AT93C86A-10SU-2.7-T			2.7V to 5.5V ⁽¹⁾	Tape and Reel	4,000 per Reel		
AT93C86A-10TU-1.8	Matte Tin Lead-free Halogen-free			1.8V to 5.5V	Bulk (Tubes)	100 per Tube	
AT93C86A-10TU-1.8-T		8X	1.8V to 5.5V	Tape and Reel	5,000 per Reel		
AT93C86A-10TU-2.7		0.4	2.7V to 5.5V ⁽¹⁾	Bulk (Tubes)	100 per Tube		
AT93C86A-10TU-2.7-T			2.7V to 5.5V ⁽¹⁾	Tape and Reel	5,000 per Reel		
AT93C86A-10PU-1.8		8P3	1.8V to 5.5V	Bulk (Tubes)	50 per Tube		
AT93C86A-10PU-2.7		ors	2.7V to 5.5V ⁽¹⁾	Bulk (Tubes)	50 per Tube		
AT93C86AY6-10YH-1.8-T	NiPdAu Lead-free	8MA2	1.8V to 5.5V	Tape and Reel	5,000 per Reel		
AT93C86AY6-10YH-18-E	Halogen-free	OWIAZ	1.67 (0 5.57	Tape and Reel	15,000 per Reel		

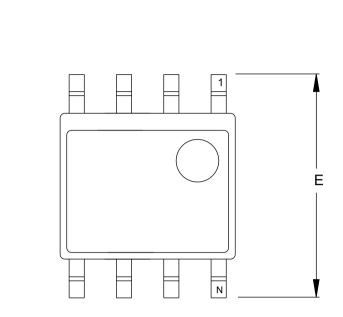
Notes: 1. For 2.7V devices used in a 4.5V to 5.5V range, please refer to performance values in Section 4.2, "DC Characteristics" and 4.3, "AC Characteristics" on page 5.

	Package Type						
8S1	8-lead, 0.150" wide, Plastic Gull Wing, Small Outline (JEDEC SOIC)						
8X	8-lead, 0.170" wide, Thin Shrink Small Outline (TSSOP)						
8P3	8-lead, 0.300" wide body, Plastic Dual In-line Package (PDIP)						
8MA2	8-pad, 2.00mm x 3.00mm body, 0.50mm pitch, Ultra Thin Dual No Lead (UDFN)						

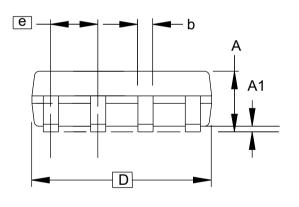


10. Packaging Information

10.1 8S1 — 8-lead JEDEC SOIC



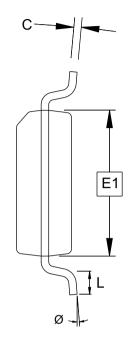
TOP VIEW



SIDE VIEW

Notes: This drawing is for general information only.

Refer to JEDEC Drawing MS-012, Variation AA for proper dimensions, tolerances, datums, etc.



END VIEW

COMMON DIMENSIONS (Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
А	_	_	1.75	
A1	0.10	_	0.25	
b	0.31	_	0.51	
С	0.17	_	0.25	
D		4.90 BSC	,	
Е	(6.00 BSC	;	
E1	;	3.90 BSC	;	
е				
L	0.40	_	1.27	
Ø	0°	_	8°	

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REV.

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Atmel

Package Drawing Contact: packagedrawings@atmel.com

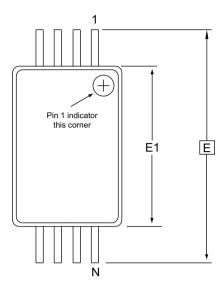
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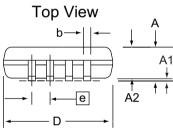
GPC DRAWING NO.
SWB 8S1

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14

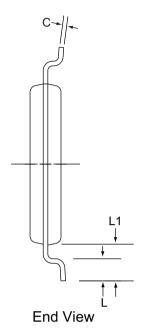
10.2 8X — 8-lead TSSOP





Side View

- Notes: 1. This drawing is for general information only. Refer to JEDEC Drawing MO-153, Variation AA, for proper dimensions, tolerances, datums, etc.
 - 2. Dimension D does not include mold Flash, protrusions or gate burrs. Mold Flash, protrusions and gate burrs shall not exceed 0.15mm (0.006in) per side.
 - 3. Dimension E1 does not include inter-lead Flash or protrusions. Inter-lead Flash and protrusions shall not exceed 0.25mm (0.010in) per side.
 - 4. Dimension b does not include Dambar protrusion. Allowable Dambar protrusion shall be 0.08mm total in excess of the b dimension at maximum material condition. Dambar cannot be located on the lower radius of the foot. Minimum space between protrusion and adjacent lead is 0.07mm.
 - 5. Dimension D and E1 to be determined at Datum Plane H.



COMMON DIMENSIONS (Unit of Measure = mm)

	(Onit C	n wicasarc	,	
SYMBOL	MIN	NOM	MAX	NOTE
А	-	-	1.20	
A1	0.05	-	0.15	
A2	0.80	1.00	1.05	
D	2.90	3.00	3.10	2, 5
E	6.40 BSC			
E1	4.30	4.40	4.50	3, 5
b	0.19	0.25	0.30	4
е		0.65 BSC		
L	0.45	0.60	0.75	
L1	1.00 REF			
С	0.09	-	0.20	

2/27/14

A	ltm	el

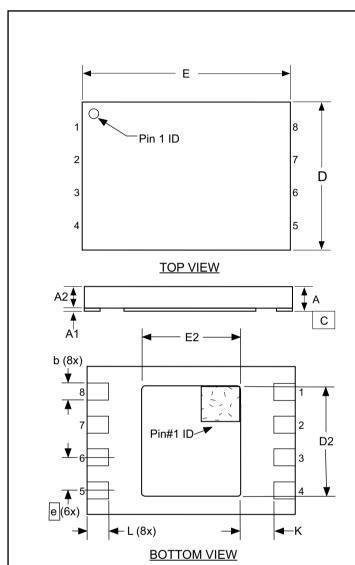
Package Drawing Contact: packagedrawings@atmel.com

TITL	.E	
8X,	8-lead 4.4mm Body,	Plastic Thin
Shri	ink Small Outline Pac	kage (TSSOP)

GPC	DRAWING NO.	REV.
TNR	8X	Е



10.3 8MA2 — 8-pad UDFN



→ C SIDE VIEW

COMMON DIMENSIONS (Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
Α	0.50	0.55	0.60	
A1	0.0	0.02	0.05	
A2	-	-	0.55	
D	1.90	2.00	2.10	
D2	1.40	1.50	1.60	
Е	2.90	3.00	3.10	
E2	1.20	1.30	1.40	
b	0.18	0.25	0.30	3
С	(0.152 REF		
L	0.35	0.40	0.45	
е		0.50 BSC		
K	0.20	-	-	

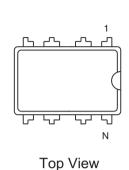
11/2/15

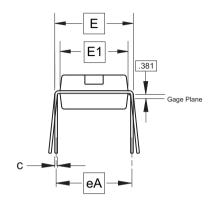
Notes:

- This drawing is for general information only. Refer to Drawing MO-229, for proper dimensions, tolerances, datums, etc.
- 2. The Pin #1 ID is a laser-marked feature on Top View.
- Dimensions b applies to metallized terminal and is measured between 0.15 mm and 0.30 mm from the terminal tip. If the terminal has the optional radius on the other end of the terminal, the dimension should not be measured in that radius area.
- 4. The Pin #1 ID on the Bottom View is an orientation feature on the thermal pad.

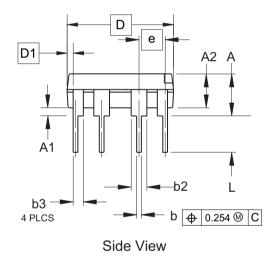
Atmel	TITLE	GPC	DRAWING NO.	REV.
Package Drawing Contact:	8MA2, 8-pad 2 x 3 x 0.6mm Body, Thermally Enhanced Plastic Ultra Thin Dual Flat No-Lead	YNZ	8MA2	Н
packagedrawings@atmel.com	Package (UDFN)			

10.4 8P3 — 8-lead PDIP





End View



COMMON DIMENSIONS (Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
Α	ı	-	5.334	2
A1	0.381	-	ı	
A2	2.921	3.302	4.953	
b	0.356	0.457	0.559	5
b2	1.143	1.524	1.778	6
b3	0.762	0.991	1.143	6
С	0.203	0.254	0.356	
D	9.017	9.271	10.160	3
D1	0.127	0.000	0.000	3
Е	7.620	7.874	8.255	4
E1	6.096	6.350	7.112	3
е	2.540 BSC			
eA	7.620 BSC		4	
L	2.921	3.302	3.810	2

Notes:

- This drawing is for general information only; refer to JEDEC Drawing MS-001, Variation BA for additional information.
 Dimensions A and L are measured with the package seated in JEDEC seating plane Gauge GS-3.
 D, D1 and E1 dimensions do not include mold Flash or protrusions. Mold Flash or protrusions shall not exceed 0.010 inch.
 E and eA measured with the leads constrained to be perpendicular to datum.
 Pointed or rounded lead tips are preferred to ease insertion.

- 6. b2 and b3 maximum dimensions do not include Dambar protrusions. Dambar protrusions shall not exceed 0.010 (0.25 mm).

07/31/14

∕Itmel	TITLE	GPC	DRAWING NO.	REV.
Package Drawing Contact: packagedrawings@atmel.com	8P3, 8-lead, 0.300" Wide Body, Plastic Dual In-line Package (PDIP)	PTC	8P3	E



11. Revision History

Revision No.	Date	Comments
3408L	01/2017	Added Bulk (Tube) Shipping Carrier Option Changed Standard Quantity Tape and Reel Option to "T" Updated Ordering Information Table Removed AT93C86A-W1.8-11 Part Number
3408K	12/2015	Correct Ordering Code Detail and update the 8S1 and 8MA2 package drawings.
3408J	01/2015	Add the UDFN extended quantity option and update the ordering information section. Update the 8MA2 and 8P3 package drawings.
34081	08/2014	Update pinouts, 8MA2 package drawing, grammatical changes, document template, logos, and disclaimer page. No changes to functional specification.
3408H	01/2007	Add "Bottom View" to page 1 Ultra Thin MiniMap package drawing page 4 revise Note 1 added "ensured by characterization".
3408G	07/2006	Revision history implemented. Delete 'Preliminary' status from datasheet; Add 'Ultra Thin' description to MLP 2x3 package; Delete '1.8V not available' on Figure 1 Note; Add 1.8V range on Table 4 under Write Cycle Time.













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